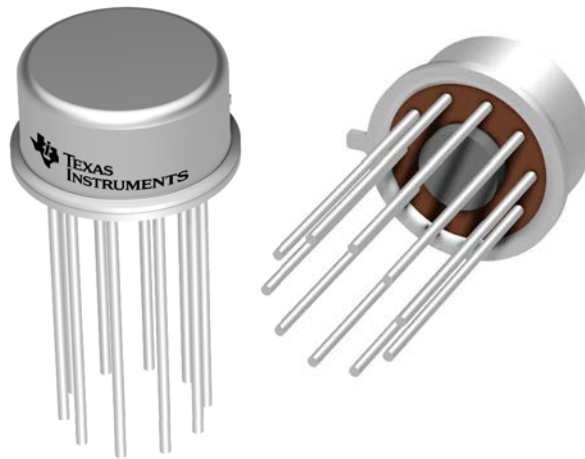


GENERIC PACKAGE VIEW

LME 10

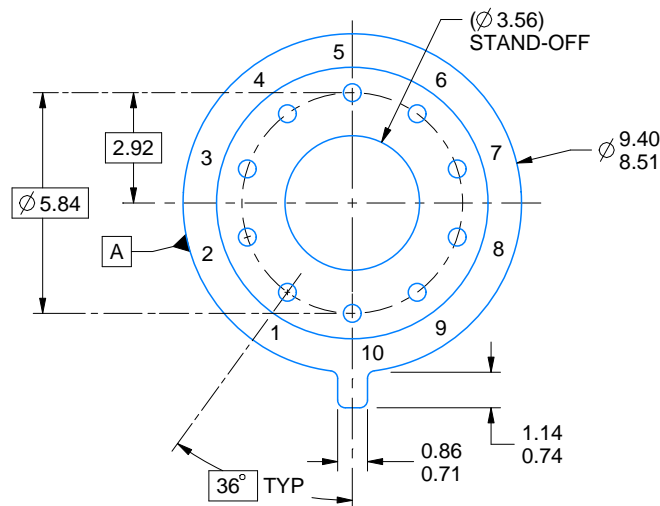
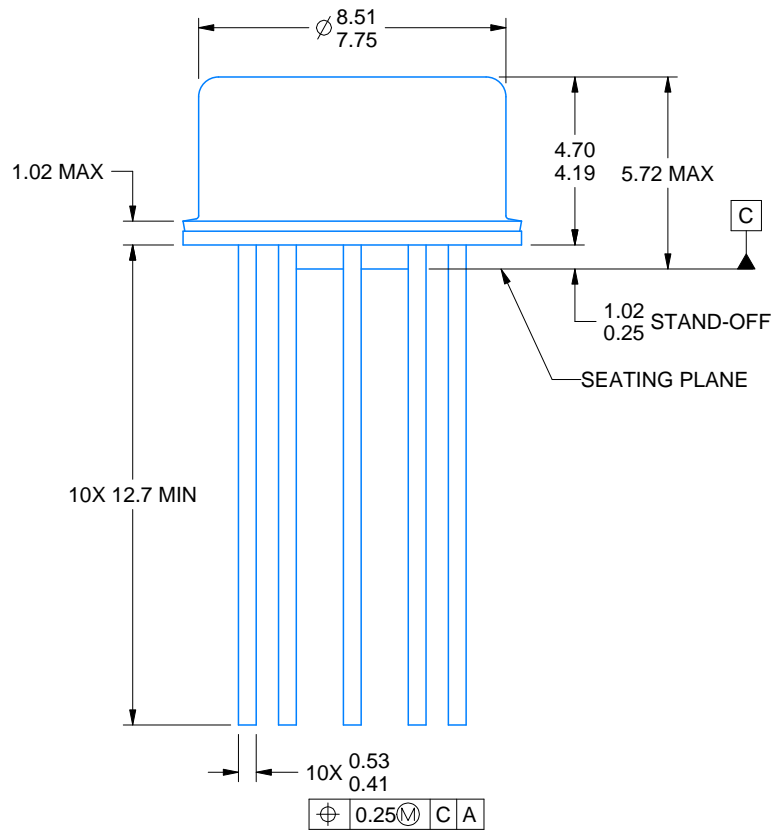
TO-CAN - 5.72 mm max height

METAL CYLINDRICAL PACKAGE



Images above are just a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.

4202488/B



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NOTES:

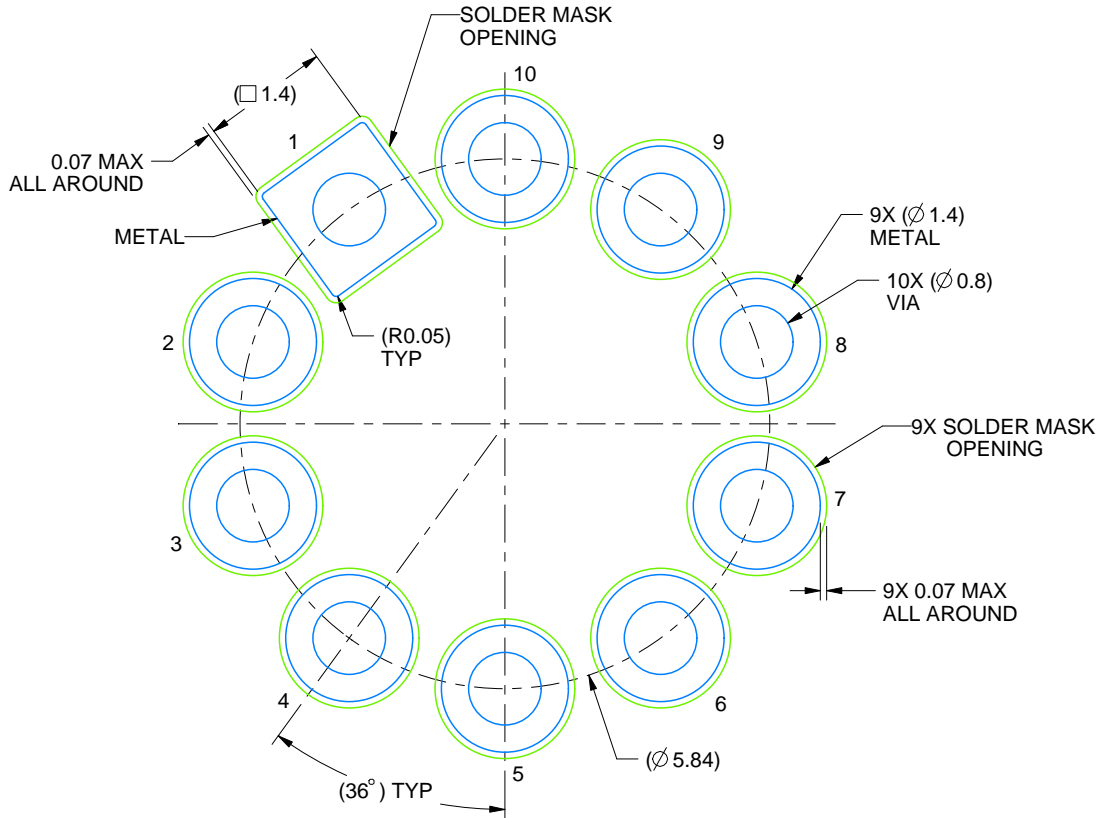
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Reference JEDEC registration MO-006/TO-100.

EXAMPLE BOARD LAYOUT

LME0010A

TO-CAN - 5.72 mm max height

METAL CYLINDRICAL PACKAGE



LAND PATTERN EXAMPLE
NON-SOLDER MASK DEFINED
SCALE: 12X

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